



EXPEDITED PROCEDURE **RESPONSE UNDER 37 CFR 1.116 GROUP ART UNIT 3724**

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

SU et al.

09/394,918 Serial No.:

Filed: September 13, 1999

SUBSTRATE SAWING PROCESS FOR A STRIP For:

Group Art Unit: 3724

Examiner: O. Flores Sanchez

AMENDMENT

Assistant Commissioner for Patents Washington, D.C. 20231

Sir:

This is in response to the Official Action of November 6, 2000, in connection with the above-identified application.

Please amend the above-identified application as follows.

IN THE CLAIMS:

Please amend claim 8 as follows.

8(Amended). The process as claimed in Claim 7, wherein the substrate strip has a longitudinal [axial] axis\and a lateral [axial] axis and the substrate areas are disposed along the longitudinal [axial] axis, the saw machine is positioned with respect to the first substrate area according to the alignment marks along the longitudinal [axial] axis from one side thereof and cuts the substrate strip according to cutting tracks defined by the cutting marks parallel to the lateral [axial] axis, then, the saw machine is positioned with respect to the hext substrate area and then cuts the substrate strip, whereby the cutting error resulted from each substrate area will not accumulate to the subsequent substrate areas in the substrate strip.

